

FFP08H60S Hyperfast Recovery Power Rectifier

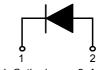
Features

- High Speed Switching
- High Reverse Voltage and High Reliability
- Avalanche Energy Rated
- Low Forward Voltage

Applications

- General Purpose
- Switching Mode Power Supply
- Free-wheeling diode for motor application
- Power switching circuits





1. Cathode 2. Anode

Absolute Maximum Ratings (per diode) T_a = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{RRM}	Peak Repetitive Reverse Voltage	600	V
V _{RWM}	Working Peak Reverse Voltage	600	V
V _R	DC Blocking Voltage	600	V
I _{F(AV)}	Average Rectified Forward Current @ T _C = 120°C	8	А
I _{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	60	A
T _{J,} T _{STG}	Operating Junction and Storage Temperature	- 65 to +150	°C

Thermal Characteristics T_a = 25°C unless otherwise noted

Symbol	Parameter	Мах	Units
R_{\thetaJC}	Maximum Thermal Resistance, Junction to Case	2.5	°C/W

Package Marking and Ordering Information

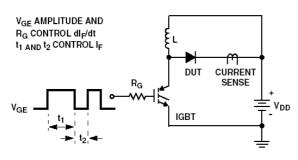
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
F08H60S	FFP08H60STU	TO-220AC	-	-	50

Symbol	Parameter		Min.	Тур.	Max.	Units
V _{FM} *	I _F = 8A I _F = 8A	T _C = 25 °C T _C = 100 °C	-	-	2.1 1.7	V V
I _{RM} *	V _R = 600V V _R = 600V	T _C = 25 °C T _C = 100 °C	-	-	100 500	μΑ μΑ
t _{rr}	I _F =1A, di/dt = 100A/µs, V _{CC} = 30V I _F =8A, di/dt = 100A/µs, V _{CC} = 390V	T _C = 25 °C T _C = 25 °C	-		35 45	ns ns
t _a t _b Q _{rr}	I _F =8A, di/dt = 100A/μs, V _{CC} = 390V	T _C = 25 °C T _C = 25 °C T _C = 25 °C	- - -	15 16 18.6		ns ns nC
W _{AVL}	Avalanche Energy (L = 40mH)		20	-	-	mJ

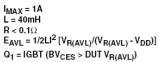
Electrical Characteristics (per diode) T_a = 25°C unless otherwise noted

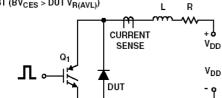
* Pulse Test: Pulse Width=300 $\mu s,$ Duty Cycle=2%

Test Circuit and Waveforms

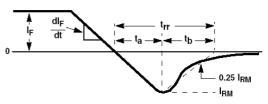


trr TEST CIRCUIT

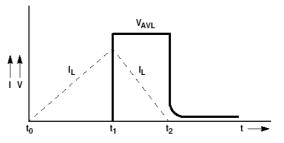




AVALANCHE ENERGY TEST CIRCUIT



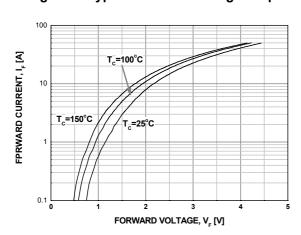
trr WAVEFORMS AND DEFINITIONS

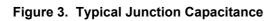


AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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Typical Performance Characteristics Figure 1. Typical Forward Voltage Drop





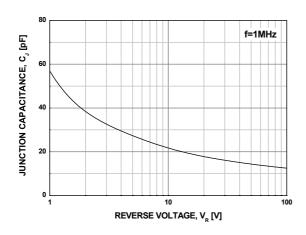


Figure 5. Typical Reverse Recovery Current

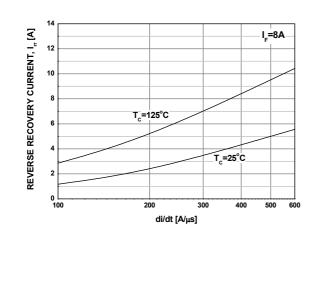


Figure 2. Typical Reverse Current

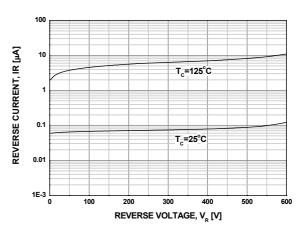


Figure 4. Typical Reverse Recovery Time

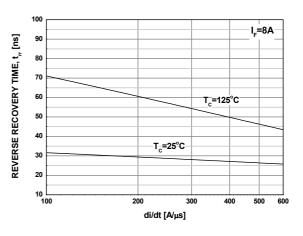
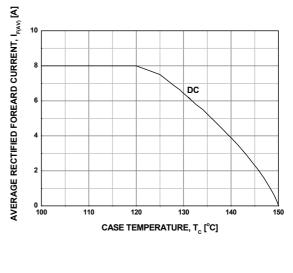
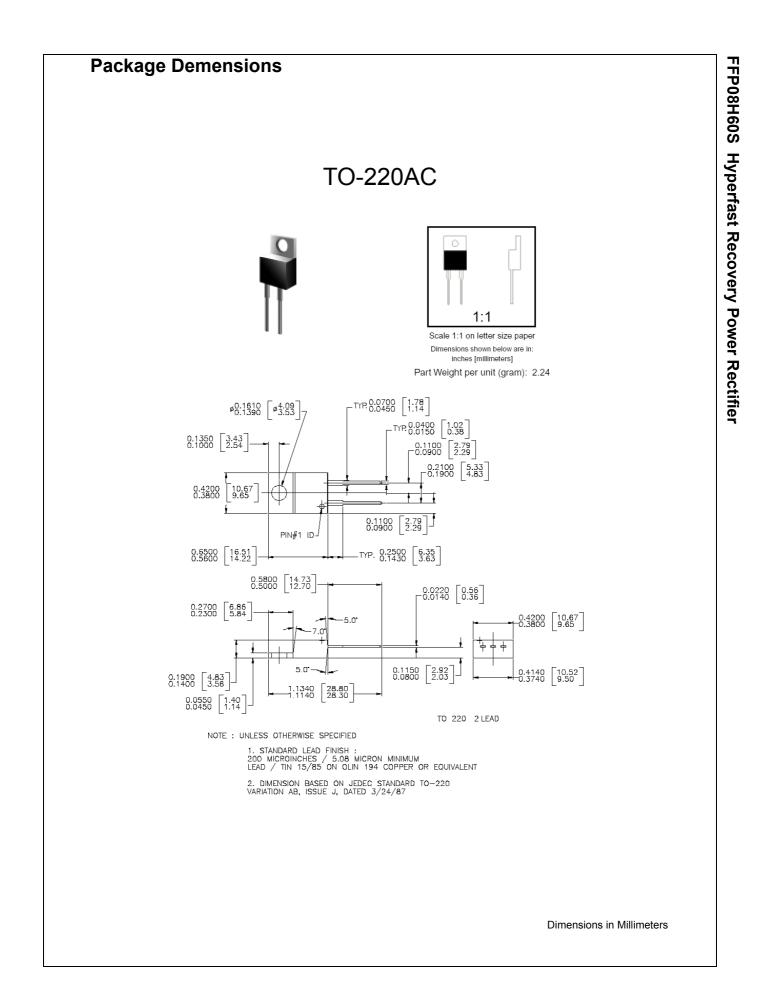


Figure 6. Forward Current Deration Curve





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